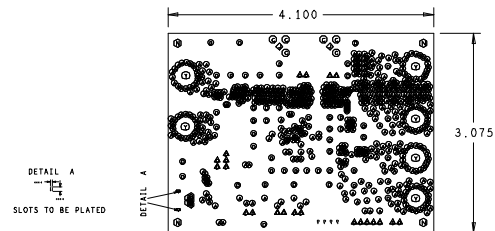


NOTE: All VIAS to be TENTED. NO exposed copper pads on any VIAS top or bottom Except VIAS in SMT pads.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
•	10.0	PLATED	646
•	28.0	PLATED	5
•	32.0	PLATED	4
⊙	37.0	PLATED	6
•	40.0	PLATED	49
▲	41.0	PLATED	22
◆	93.0	PLATED	2
⊙	236.0	PLATED	6
⊙	128.0	NON-PLATED	4
•	76.0x28.0	PLATED	2
TOTAL HOLES:			746

VIAS IN PADS TO BE FILLED WITH NON-CONDUCTIVE EPOXY

NOTES:

- THIS IS A 4 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
- PRINTED CIRCUIT BOARD SHALL BE 2 OUNCE COPPER. BOARD MATERIAL TO BE EXPOXY BASED FR-4.
-
- SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
- MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE. ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS DIRECTIVE 20002/95/EC
LAMINATE AND RESIN MATERIAL PARAMETERS
T_g > 170 C
T_d > 294 C
- ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
- MINIMUM TRACE WIDTH 8 MILS/ SPACE 6 MILS

Drawn By: MARGARET SAVIED	Date Drawn: 12/10/24	Engineer: Marc Johnson
Released By:	Date Released:	RTKA96838DE0000BU REV A
Updated By:	Date Updated:	Fabrication Drawing
	FILENAME: RTKA96838DE0000BU REV A	SHEET 1 of 1